

SMTG SERIES_表面自動黏著接地泡棉墊片 (SMT Grounding Gasket)

Product Introduction

With consumer electronics products adds more functionality and design of the smaller and thinner form factor, PCB Layout increasing complexity, may be more a function of interference of electronic products. Electronic engineers design space becomes more challenging. These challenges require additional ground to help eliminate noise, static electricity, and other electromagnetic interference. The latest laminated conductive foam material together in conjunction with copper plating automatic surface mount pads, this product also provides excellent electrical characteristics and compression resilience, there are many different sizes for customers to choose.

Product Feature

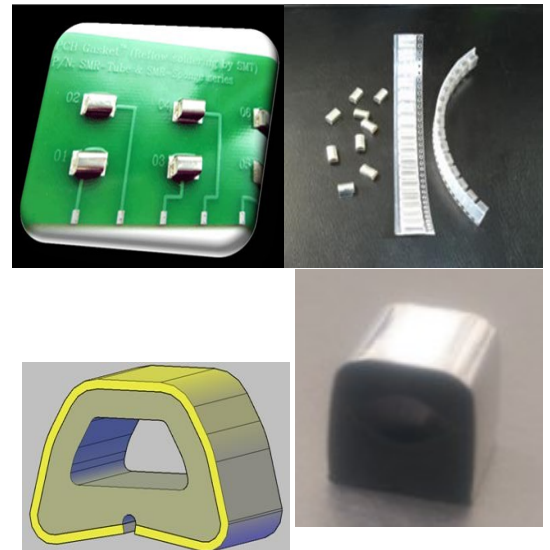
- Can be used for automated surface mount anti-electromagnetic interference protection pads.
- Reply to force high elasticity and excellent conduction performance.
- Can provide a variety of sizes and can be applied to the feasibility of Heavy Industries.
- For printed circuit board has a strong adhesion properties.
- Standardized design, saving time and cost of mold design.
- Products of high reliability, without the risk of breakage.
- EIA standardized packaging tape, high production efficiency.



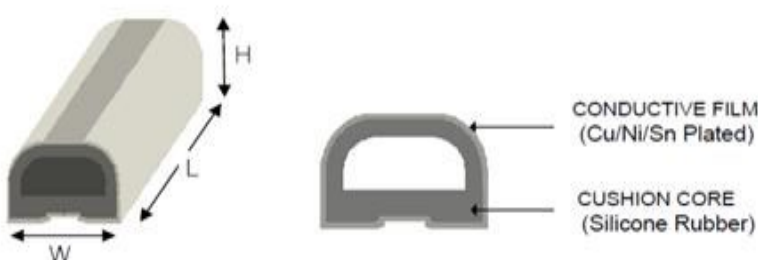
Product Photos

Product Comparison

Item / Product	Traditional foam	SMTG foam
Product portfolio	PSA	Lead-free solder
Assembly methods	Hand Work	SMT
	X	○
Bonding material	△	○
Conductive effect	△	○
Rebound effect	○	○
Packing Method	Each / Peace	EIA TAPE REEL



Product Structure



Part Number Structure

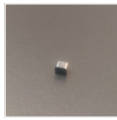

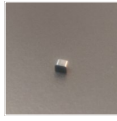

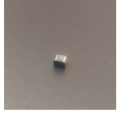


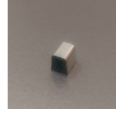




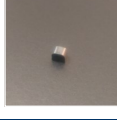
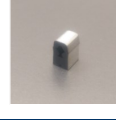


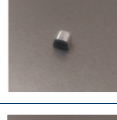



SMTG - Width - Height - Length

(1) (2) (3) (4)

- (1) Series
- (2) Width-----mm
- (3) Height-----mm
- (4) Length-----mm

表面自動黏著接地泡棉墊片 (SMT Ground Gasket)

產品規格_ Product Specifications

	Part No.	W	H	L	EA / REEL	Unit : mm		Part No.	W	H	L	EA / REEL	Unit : mm
1	SMTG-2-0.7-1	2	0.7	1.0	4000		11	SMTG-4.5-4.5-3	4	4.5	3	2000	
2	SMTG-2-2-1.5	2	2	1.5	3000		12	SMTG-4.5-5-6	4.5	5	6	1000	
3	SMTG-2.5-1.2-1	2.5	1.2	1	4000		12	SMTG-4.5-6-6	4.5	6	6	1000	
4	SMTG-3-1.5-4	3	1.5	4	6000		14	SMTG-5-6-6	5	6	6	1000	
5	SMTG-3-2-2	3	2	2	4000		15	SMTG-5-6.5-3	5	6.5	3	1500	
6	SMTG-3-2.5-2	3	2.5	2	4000		16	SMTG-5-7.5-3	5	7.5	3	1500	
7	SMTG-3-2.5-3	3	2.5	3	4000		17	SMTG-5-9-6	5	9	6	800	
8	SMTG-3-3-2	3	3	2	3000		18	SMTG-7-7-5	7	7	5	1000	
9	SMTG-4-3.5-3	4	3.5	3	3000		19	SMTG-8-9.5-10	8	9.5	10	500	
10	SMTG-4-4-3	4	4	3	3000		20	SMTG-10-12-8.4	10	12	8.5	500	

* If there is no more than the size you need, feel free to contact virtuous technology sales engineers, we will soon proofing and you need to provide a sample.

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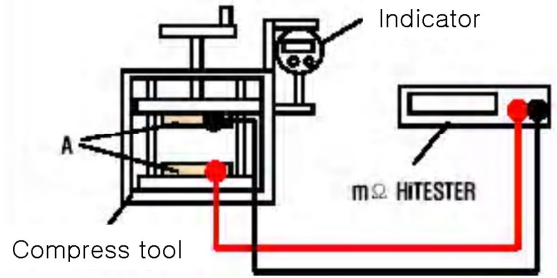
Test Report

Compression ratio & Resistance

Connect the following compression testing machine with micro ohm tester

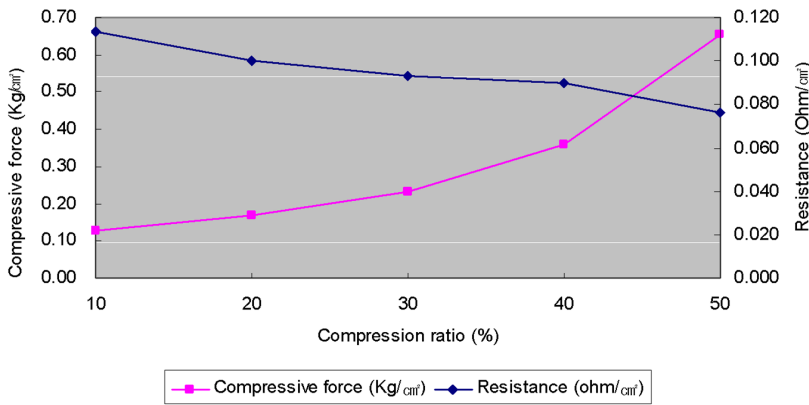
B. sample was placed in the test at A side

C. compression set resistance, compression testing machine after the start, from which to read through the micro-Farm compression ratio values.



Test Specification Report-----SMTG-4.5-4.5-6

Compressive force & Resistance



Compression Rate (%)	Compressive Load (kg/cm ²)	Resistance (Ω / cm ²)
10	0.12	0.10
20	0.18	0.07
30	0.25	0.04
40	0.38	0.03
50	0.67	0.02

	Before (t : mm)	After (t : mm)	Respond (%)
1	4.46	4.45	99.77
2	4.52	4.46	98.67
3	4.51	4.47	99.11
4	4.48	4.48	100.00
5	4.51	4.47	99.11
6	4.49	4.46	99.33
7	4.53	4.45	98.23
8	4.49	4.44	98.88
9	4.51	4.43	98.22
10	4.52	4.45	98.45
	4.5 (AVG.)	4.46(AVG.)	98.98(AVG.)

Reply compression test mode

A. Measuring the thickness of the sample

B. at a temperature of 70 ° C ± 1 ° C of the state, the compression test sample to 50%, sequential compression 22 hours

C. After 22 hours the compression, left to stand at room temperature for 30 minutes and then measure the thickness of the sample

$$C = \{1 - [t0-t1 / t0]\} \times 100$$

t0 = Thickness (Before)-mm

t1 = Thickness (After)-mm

Pull force test

The lead-free solder SMT Gasket way to mount printed circuit board.

The board fixed, with the power of the speed of 50mm per minute, by the side thrust to SMT Gasket.

In SMT Gasket totally isolated since the printed circuit board, the calculated value of the pulling force.

Environmental Testing

RoHS Compliant (Halogen Free & Pb Free) BY SGS TEST REPORT

High temperature accelerated life test: TEST REPORT BY SGS / ETC LAB.

Anti-electromagnetic performance tests: 65dB (AVG.) E5062 Vector Network Analyzer From 30MHz to 3GHz

Test P/N	Drawing Force (kgf)
SMTG-4.5-4.5-6.0	3.0 (Minimum)
SMTG -4.0-4.0-6.0	2.5 (Minimum)
SMTG-3.0-2.0-2.0	1.0 (Minimum)

